

CHIP SCHOTTKY BARRIER DIODES

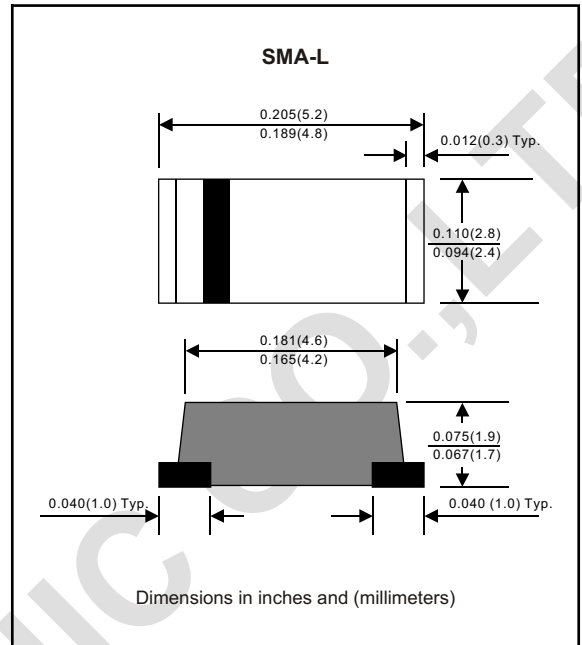
Glass passivated type

FEATURES

- Plastic package gas Underwriters Laboratory Flammability Classification 94V-O Utilizing Flame Retardant Epoxy Molding Compound.
- For surfact mounted applications.
- Exceeds environmental standards of MIL-S-19500/228
- Low leakage current.

MECHANICAL DATA

- **Case:** Molded plastic, JEDEC DO-241AC
- **Terminals:** Solder plates, solderable per MIL-STD-750 Method 2026
- **Polarity:** Indicated by cathode end
- **Mounting position:** Any
- **Weight:** 0.0015 ounce, 0.05 gram



MAXIMUM RATINGS (AT T_A= 25°C unless otherwise note)

PARAMETER	CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNITS
Forward rectified current	Lead temperature = 90°C	I _o			1.0	A
Forward surge current	8.3ms single half sine-wave superimposed on rate load (JEDEC methode)	I _{FSM}			25	A
Reverse current	V _R = V _{RRM} T _A = 25°C	I _R			0.5	mA
	V _R = V _{RRM} T _A = 125°C				10	mA
Thermal resistance	Junction to ambient	R _{θJA}			95	°C/W
Diode junction capacitance	F = 1MHz and applied 4vDC reverse voltage	C _J		15		pF
Operating temperature		T _J	-55		+150	°C

SYMBOL	MARKING CODE	V _{RRM} ^{*1} (v)	V _{RMS} ^{*2} (v)	V _R ^{*3} (v)	V _F ^{*4} (v)	Storage temperature (°C)
FM5817	SK12	20	14	20	0.45	-55 to +150
FM5818	SK13	30	21	30	0.55	
FM5819	SK14	40	28	40	0.60	

*1 Repetitive peak reverse voltage

*2 RMS voltage

*3 Continuous reverse voltage

*4 Forward rectified current

RATING AND CHARACTERISTIC CURVES

FIG.1 TYPICAL FORWARD CURRENT DERATING CURVE

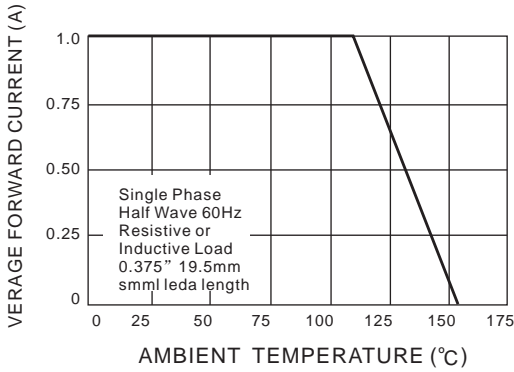


FIG.2 TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

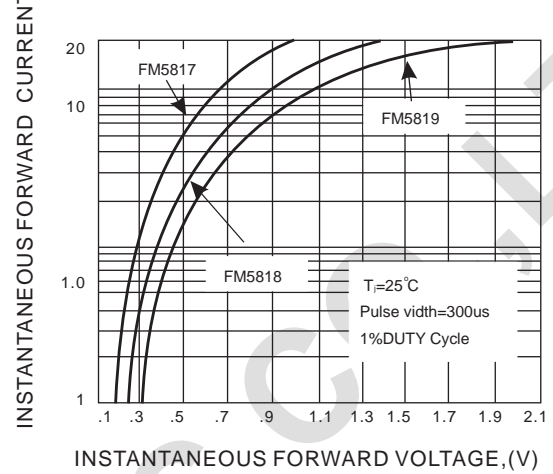


FIG.3 TYPICAL REVERSE CHARACTERISTICS

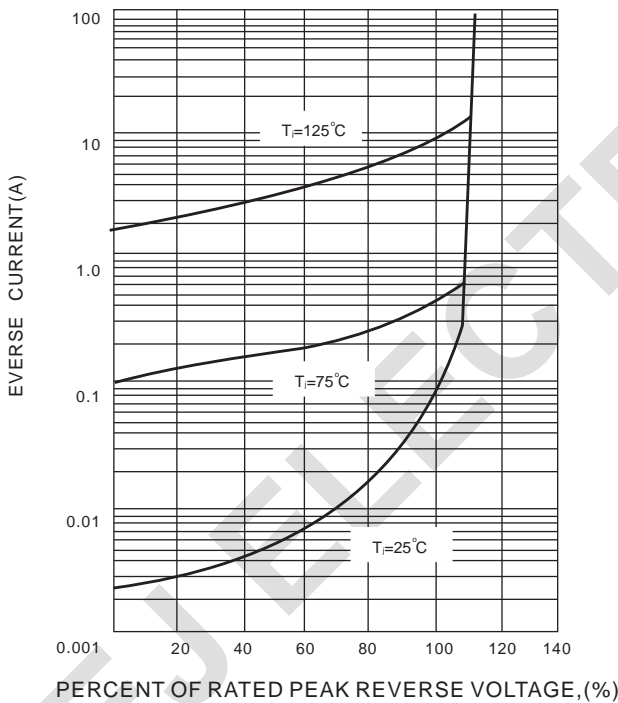


FIG.4 -MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

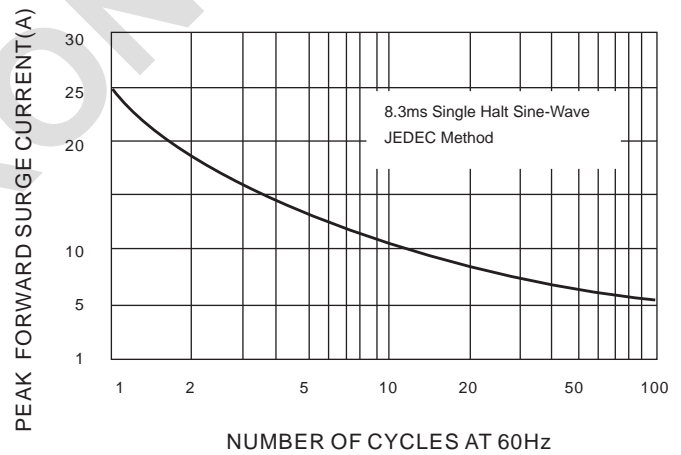


FIG.5 TYPICAL JUNCTION CAPACITANCE

